

### **Booth #B6**

# ELSFP External Laser Small Form Factor Pluggable

Eliminate CPO switch downtime with modular 'hot-swappable' laser sources

The External Laser Small Form-Factor Pluggable (ELSFP) is a pioneering blind-mating optical and electrical interconnect in a convenient pluggable industry recognized OSFP-RHS approximate footprint. The ELSFP is optimized to support next-generation co-packaged optics (CPO) requiring a remote laser source.

Module and Host Connectors

SENKO's innovative design allows the laser module to be quickly and easily 'blind-mated' to the host connectors mounted within the CPO switch.

Standardized by our

Hyperscale
Densification with
VSFF
Connectivity



SENKO's **SN-MT** Connectivity optimizes patch panel densification and enables the front panel space for the ELSFP modules.

MODULE CONNECTOR

HOST CONNECTOR



#### FEATURE

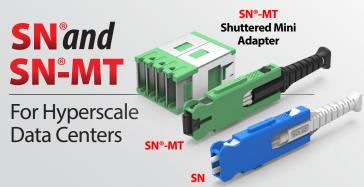
- · Reduced overall system thermal power density
- Fast 'plug & play' design for fast deployment
- · Compact design enables maximum face-plate density
- A single ELSFP can support multiple OEs
- Hot swappable to prevent system downtime
- Eye-safe design
- Approximate OSFP-RHS envelope
- PM fiber assemblies for the interconnect between
- ELSFP and CPO engines

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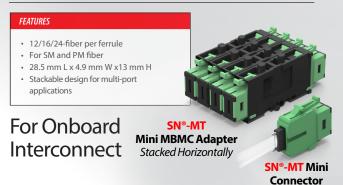
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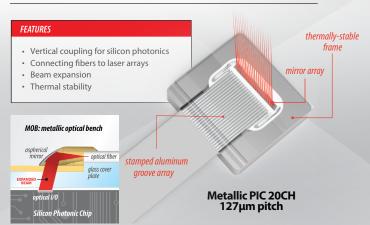
## Faceplate Densification



## **SN-MT** *Mini MBMC Adapter*



### **MPC** *Metallic PIC Connector*



MPO PLUS®

#### FEATURES

- Compatible with dual MPO transceivers
- Fortified soft spring design
- Industry leading IL 0.25dB
- Reduced footprint for perfect fit

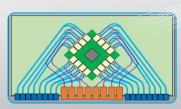


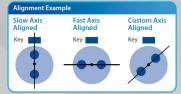
Tailored for Dual 800G Transceivers

### MT-MPO Adapter



#### Fiber Assemblies







#### MT Ferrules

MT ferrule assemblies with PM fibers meeting ELSFP requirements





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